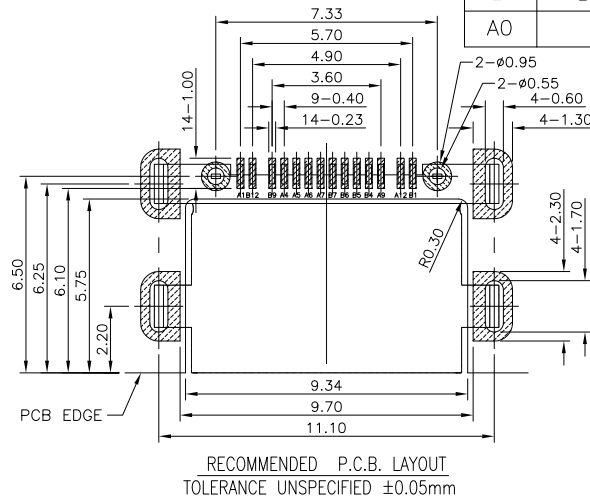
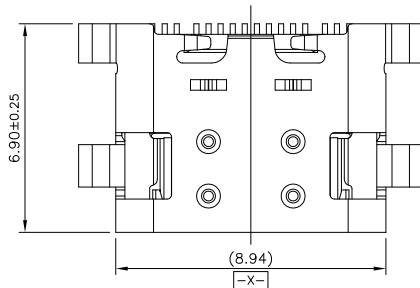


GP Component

REV.	ECN NO.	LOCATIONS	DESCRIPTION	DATE	DESIGN
AO			Initial	2017/07/28	Phebe Su



NOTES:

1.MATERIAL:

MOLDING: LCP BLACK UL94 V-0

CONTACT: COPPER ALLOY.

GOLD FLASH PLATED Min ON CONTACT AREA,
100u" Min TIN (LEAD FREE) ON SOLDER AREA,

SHELL: SUS304-H,T=0.30±0.03mm

50u" NICKEL PLATING OVER ALL.

SHILD: SUS304-H,T=0.12±0.03mm

2.MECHANICAL:

INSERTION: 5~20N.

EXTRACTION: 8~20N AFTER TEST.

DURABILITY: 10000 CYCLES

3.ELECTRICAL:

CURRENT: 5A FOR VBUS;

1.25A FOR GND PIN.

0.25A FOR OTHER.

VOLTAGE: 20 V MAX

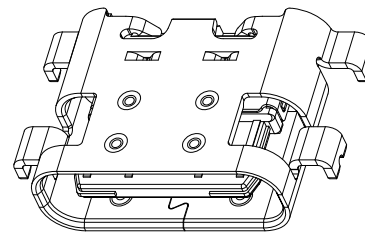
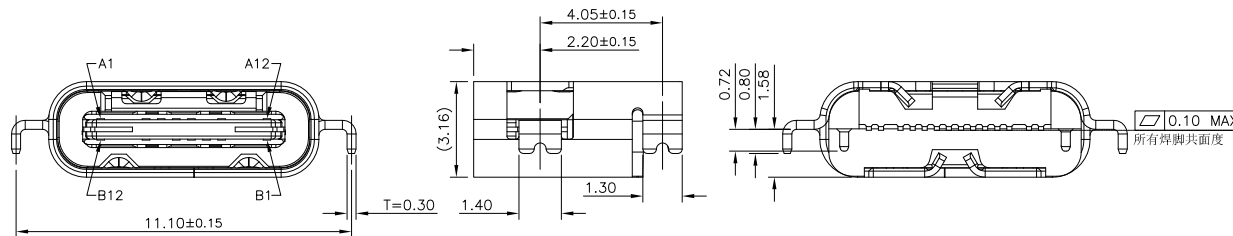
WITHSTANDING VOLTAGE: 100V AC R.M.S.

CONTACT RESISTANCE: 40mΩ MAX.

INSULATION RESISTANCE: 100MΩ MIN.

4.ENVIRONMENTAL

TEMPERATURE RANGE -40°C ~ +85°C



MATRIX PART NO:

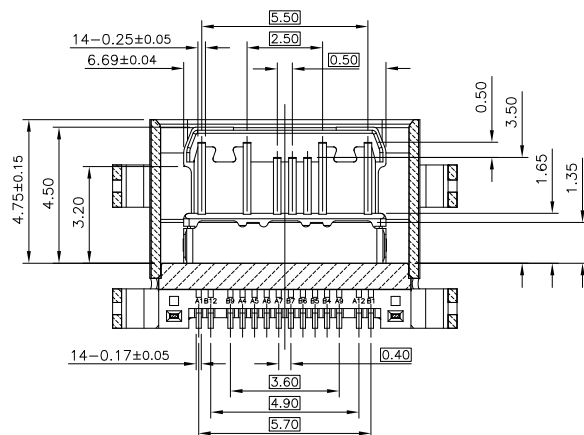
MUSB12-01-252

MATRIX USB

Pin Number

Series number

Plating
01:Gold Flash
15:15u"
30:30u"



A1	GND	B12	GND
A4	VBUS	B9	VBUS
A5	CC1	B7	DN2
A6	DP1	B6	DP2
A7	DN1	B5	CC2
A9	VBUS	B4	VBUS
A12	GND	B1	GND
PIN	SIGNAL NAME	PIN	SIGNAL NAME



Matrix Electronics Co.,Ltd

TOLERANCE: X.X ±0.25 X.XX ±0.15 X.XXX ±0.05 ANGLE: ±3°	DESIGN BY : Phebe Su	DATE : 2017/07/28	PART NAME: USB 2.0 Type C Female R/A, Offset type, CL 0
APPROVED BY1: Richard Hsieh	CHECKED BY: Vicky Hsieh	DATE : 2017/07/28	PART NO. MUSB12-01-252
APPROVED BY2: Richard Hsieh	DATE : 2017/07/28	MOLD NO. NA	DRAW NO.
SCALE:1:1	SIZE:A4	SHEET NO.	1 OF 1